



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAIR® 6 x 5					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	280	140 000	200 °C + N2	0	0.00
HAST	440	44 000	130 °C, 85 % RH	0	0.00
Pressure Pot	440	42 240	121°, 15 PSIG	0	0.00
Solder DUNK	110	330	260 °C, 10 s	0	0.00
Solderability	45	360	883 M2003	0	0.00
Temp. Cycle	275	142 010	- 65 °C to 150 °C	0	0.00